Features



# /VI/IXI/VI

## +5V Single-Supply, 1Msps, 16-Bit Self-Calibrating ADC

## General Description

The MAX1200 16-bit, monolithic, analog-to-digital converter (ADC) is capable of conversion rates up to 1Msps. This CMOS integrated circuit uses a fully differential, pipelined architecture with digital error correction and a short self-calibration to ensure 16-bit linearity at full sample rates. An on-chip track/hold (T/H) maintains superb dynamic performance up to the Nyquist frequency. The MAX1200 operates from a single +5V supply.

The fully differential inputs allow an input swing of ±VREF. The reference is also differential with the positive reference (RFPF) typically connected to +4.096V and the negative reference (RFNF) connected to analog ground. Additional sensing pins (RFPS, RFNS) are provided to compensate for any resistive divider action that may occur. A single-ended input is also possible using two operational amplifiers.

Power dissipation is typically only 273mW at +5V, at a sampling rate of 1Msps. The device employs a CMOScompatible, 16-bit parallel, two's complement output data format. For a higher sampling speed (up to 2.2Msps) but lower resolution (14-bit), select the MAX1201, a pin-compatible version of the MAX1200.

The MAX1200 is available in an MQFP package and operates over the commercial (0°C to +70°C) and extended-industrial (-40°C to +85°C) temperature ranges.

Applications

High-Resolution Imaging Communications Scanners

Data Acquisition Instrumentation

♦ Monolithic 16-Bit, 1Msps A/D Converter

♦ Single +5V Supply

♦ ±VREF Differential Input Voltage Range

♦ 87dB SNR for f<sub>IN</sub> = 100kHz

♦ 91dB SFDR for fin = 100kHz

♦ 273mW Low-Power Dissipation

**♦** ±0.5LSB Differential Nonlinearity Error

♦ Three-State, Two's Complement Output Data

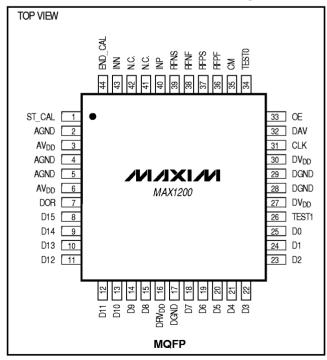
♦ On-Demand Self-Calibration

♦ Pin-Compatible 14-Bit Versions Available (1Msps MAX1205, 2.2Msps MAX1201)

Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE	DNL (LSB)
MAX1200ACMH	0°C to +70°C	44 MQFP	±0.5
MAX1200BCMH	0°C to +70°C	44 MQFP	_
MAX1200AEMH	-40°C to +85°C	44 MQFP	±0.5
MAX1200BEMH	-40°C to +85°C	44 MQFP	_

## Pin Configuration



MIXIM

Maxim Integrated Products 1

## **ABSOLUTE MAXIMUM RATINGS**

AVDD to AGND, DGND+7V
DV <sub>DD</sub> to DGND, AGND+7V
DRV <sub>DD</sub> to DGND, AGND+7V
INP, INN, RFPF, RFPS,
RFNF, RFNS, CLK, CM(AGND - 0.3V) to (AVDD + 0.3V)
Digital Inputs to DGND0.3V to (DV <sub>DD</sub> + 0.3V)
Digital Output (DAV) to DGND0.3V to (DRV <sub>DD</sub> + 0.3V)
Other Digital Outputs to DGND0.3V to (DRV <sub>DD</sub> + 0.3V)

Continuous Power Dissipation (TA = +70°	C)
44-Pin MQFP (derate 11.11mW/°C abor	ve +70°C)889mW
Operating Temperature Ranges (TA)	
MAX1200_CMH	0°C to +70°C
MAX1200_EMH	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, V_{RFPS} = +4.096V, V_{RFNS} = AGND, V_{CM} = +2.048V, V_{IN} = -0.5dBFS, f_{CLK} = 2.048MHz; digital output load <math>\leq 20pF$ ;  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG INPUT			ı			1
Input Voltage Range (Note 2)	Visi	Single-ended		4.096		v
	V <sub>IN</sub>	Differential		±4.096		7 <b>'</b>
Input Resistance (Note 3)	Ri			55		kΩ
Input Capacitance	Cı	Per side in track mode		21		pF
EXTERNAL REFERENCE	'					1
Reference Voltage (Note 4)	V <sub>REF</sub>			4.096	4.5	V
Reference Input Resistance	R <sub>REF</sub>		700	1000		Ω
TRANSFER CHARACTERISTIC	S					1
Resolution (No missing codes; Note 5)	RES	After calibration, guaranteed for MAX1200A only	16			Bits
Integral Nonlinearity	INL			±3.5		LSB
Differential Namina and	DNL	MAX1200A	-1	±0.5	+1	LSB
Differential Nonlinearity	DINL	MAX1200B		±0.6		LOB
Offset Error			-0.2	±0.003	+0.2	%FSR
Gain Error			-5	-3	5	%FSR
Input-Referred Noise				75		μV <sub>RMS</sub>
DYNAMIC SPECIFICATIONS (N	lote 6)		·			•
Maximum Sampling Rate	fSAMPLE	fsample = fclk/2	1.024			Msps
Conversion Time (Pipeline Delay/Latency)				4		f <sub>SAMPLE</sub> Cycles
Acquisition Time	tACQ	To full-scale step (0.006%)		125		ns
Overvoltage Recovery Time	tovr			450		ns
Aperture Delay	tad			3		ns
Aperture Jitter	t <sub>A</sub> J			5		ps <sub>RMS</sub>
Full-Power Bandwidth				3.3		MHz
Small-Signal Bandwidth				78		MHz

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, V_{RFPS} = +4.096V, V_{RFNS} = AGND, V_{CM} = +2.048V, V_{IN} = -0.5dBFS, f_{CLK} = 2.048MHz;$  digital output load  $\leq$  20pF; T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 1)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
		1,0001	f <sub>IN</sub> = 99.5kHz	83	87		
Signal-to-Noise Ratio		$V_{RFPS} = 4.096V,$ $V_{RFNS} = AGND$	f <sub>IN</sub> = 300.5kHz		84		dB
	SNR	VIIINS - ACIVE	$f_{\text{IN}} = 504.5 \text{kHz}$		83		
(Note 5)	SIND	0.514	f <sub>IN</sub> = 99.5kHz	78	83		
		V <sub>RFPS</sub> = 3.5V, V <sub>RFNS</sub> = 1.5V	f <sub>IN</sub> = 300.5kHz		81		
		VIIINS - 1.00	f <sub>IN</sub> = 504.5kHz		80		
		1,0001	f <sub>IN</sub> = 99.5kHz	84	91		
		$V_{RFPS} = 4.096V,$ $V_{RFNS} = AGND$	f <sub>IN</sub> = 300.5kHz		89		
Spurious-Free Dynamic Range	SFDR	AULINO - MOMP	$f_{\text{IN}} = 504.5 \text{kHz}$		88		dB
(Note 5)	SEDIN	2 5 1	f <sub>IN</sub> = 99.5kHz	85	92		uБ
		$V_{RFPS} = 3.5V$ , $V_{RFNS} = 1.5V$	f <sub>IN</sub> = 300.5kHz		91		
		VIIINS - 1.00	$f_{\text{IN}} = 504.5 \text{kHz}$		90		
			f <sub>IN</sub> = 99.5kHz		-87	-82	
Total Harmonic Distortion		V <sub>RFPS</sub> = 4.096V, V <sub>RFNS</sub> = AGND	f <sub>IN</sub> = 300.5kHz		-86		
	THD		f <sub>IN</sub> = 504.5kHz		-85		٩D
(Note 5)	IHD	V <sub>RFPS</sub> = 3.5V, V <sub>RFNS</sub> = 1.5V	f <sub>IN</sub> = 99.5kHz		-90	-84	- dB -
			f <sub>IN</sub> = 300.5kHz		-89		
			f <sub>IN</sub> = 504.5kHz		-88		
			f <sub>IN</sub> = 99.5kHz	80	84		- dB
		$V_{RFPS} = 4.096V,$ $V_{RFNS} = AGND$	f <sub>IN</sub> = 300.5kHz		82		
Signal-to-Noise Ratio plus	SINAD	VHENS - AGIND	$f_{\text{IN}} = 504.5 \text{kHz}$		81		
Distortion (Note 5)	SINAD	V <sub>RFPS</sub> = 3.5V, V <sub>RFNS</sub> = 1.5V	f <sub>IN</sub> = 99.5kHz	77	82		
			f <sub>IN</sub> = 300.5kHz		80.5		
		VHFNS - 1.5V	f <sub>IN</sub> = 504.5kHz		79.5		
POWER REQUIREMENTS							
Analog Supply Voltage	AV <sub>DD</sub>			4.75	5	5.25	٧
Analog Supply Current	I(AV <sub>DD</sub> )				51	70	mA
Digital Supply Voltage	DV <sub>DD</sub>			3		5.25	٧
Digital Supply Current	I(DV <sub>DD</sub> )				0.4	1.2	mA
Output Drive Supply Voltage	DRV <sub>DD</sub>			3		$DV_DD$	٧
Output Drive Supply Current	I(DRV <sub>DD</sub> )	10pF loads on D0–D	15 and DAV		0.1	0.6	mA
Power Dissipation	PDSS				273	377	mW
Warm-Up Time					0.1		sec
Power-Supply Rejection Ratio	PSRR	Offset		55			dB
- ower-oupply hejection hatto	I OI II I	Gain		55			

## TIMING CHARACTERISTICS (Figures 7, 8, 9)

 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, f_{CLK} = 2.048MHz, T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Conversion Time	tconv			4/fsample		ns
Clock Period	tclk			488		ns
Clock HIGH Time	tсн		187	244	301	ns
Clock LOW Time	t <sub>CL</sub>		187	244	301	ns
Acquisition Time	tACQ			t <sub>CLK</sub> / 2		ns
Output Delay	toD			70	150	ns
DAV Pulse Width	tDAV			1 / f <sub>CLK</sub>		ns
CLK-to-DAV Rising Edge	ts			65	145	ns
Data Access Time	tac	C <sub>L</sub> = 20pF		16	75	ns
Bus Relinquish Time	t <sub>REL</sub>			16	75	ns
Calibration Time	tCAL	ST_CAL = DV <sub>DD</sub>		17,400		f <sub>CLK</sub> Cycles

#### DIGITAL INPUT AND OUTPUT CHARACTERISTICS

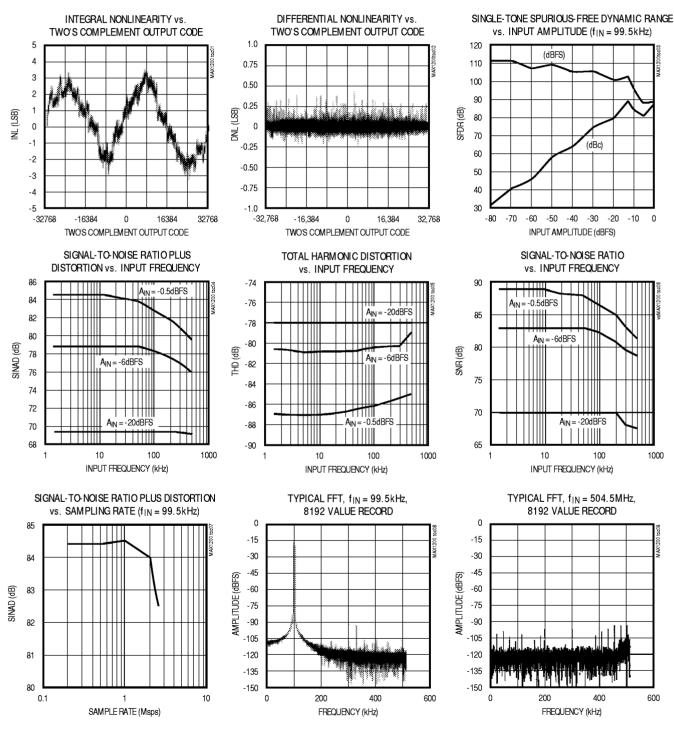
 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input LOW Voltage	V <sub>IL</sub>				0.8	٧
Input HIGH Voltage	V <sub>IH</sub>		DV <sub>DD</sub> -	0.8		٧
Input Capacitance				4		pF
CLK Input LOW Voltage	VCLK				0.8	٧
CLK Input HIGH Voltage	VCLK		AV <sub>DD</sub> -	0.8		٧
CLK Input Current	Iclk	$V_{IN} = 0$ or $V_{DD}$		±1	±10	μA
CLK Input Capacitance	C <sub>CLK</sub>			9		pF
Digital Input Current	I <sub>IN</sub>	$V_{IN} = 0$ or $DV_{DD}$		±0.1	±10	μA
Output Low Voltage	V <sub>OL</sub>	I <sub>SINK</sub> = 1.6mA		70	400	mV
Output High Voltage	V <sub>OH</sub>	ISOURCE = 200µA	DV <sub>DD</sub> - 0.4	DV <sub>DD</sub> - 0.03		V
Three-State Leakage Current	ILEAKAGE			±0.1	±10	μA
Three-State Output Capacitance	C <sub>OUT</sub>			3.5		pF

- Note 1: Reference inputs driven by operational amplifiers for Kelvin-sensed operation.
- Note 2: For unipolar mode, the analog input voltage,  $V_{INP}$ , must be within 0 and  $V_{REF}$ ,  $V_{INN} = V_{CM} / 2$ ; where  $V_{REF} = V_{RFPS} V_{RFNS}$ . For differential mode, the analog input voltages  $V_{INP}$  and  $V_{INN}$  must be within 0 and  $V_{REF}$ ; where  $V_{REF} = V_{RFPS} V_{RFNS}$ . The common-mode voltage of the inputs INP and INN is  $V_{CM} = (V_{RFPS} + V_{RFNS}) / 2$ .
- **Note 3:** R<sub>|</sub> varies inversely with sample rate.
- Note 4: Minimum and maximum parameters are not tested. Guaranteed by design.
- **Note 5:** Calibration remains valid for temperature changes within ±20°C and power-supply variations ±5%. Guaranteed by design.
- Note 6: All AC specifications are shown for the differential mode.

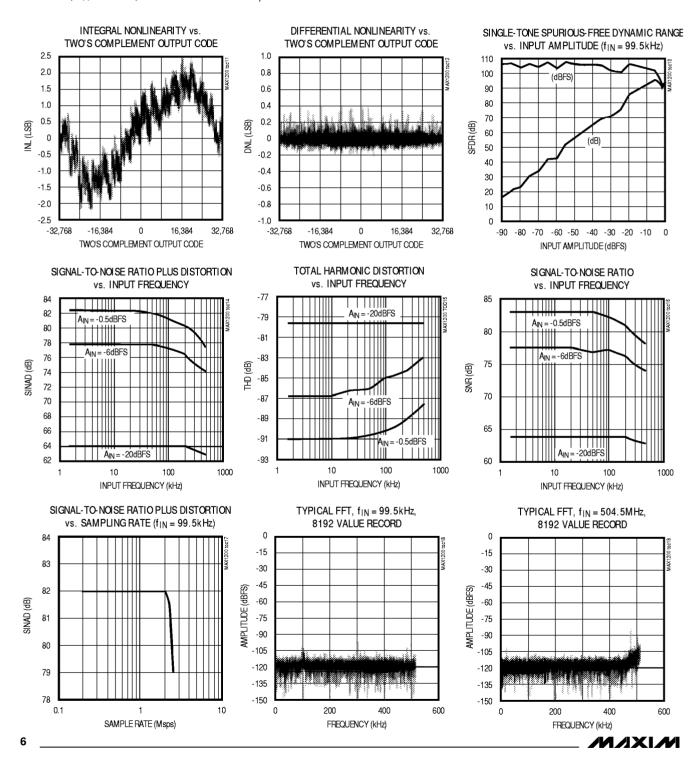
## Typical Operating Characteristics

 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, V_{RFPS} = +4.096V, V_{RFNS} = AGND; V_{CM} = +2.048V, differential input, f_{CLK} = 2.048MHz, calibrated, T_A = +25°C, unless otherwise noted.)$ 



## Typical Operating Characteristics

 $(AV_{DD} = +5V \pm 5\%, DV_{DD} = DRV_{DD} = +3.3V, V_{RFPS} = +3.5V, V_{RFNS} = +1.5V; V_{CM} = +2.5V, differential input, f_{CLK} = 2.048MHz, calibrated, T_A = +25°C, unless otherwise noted.)$ 



\_Pin Description

PIN	NAME	FUNCTION			
1	ST_CAL	Digital Input to Start Calibration.  ST_CAL = 0: Normal conversion mode.  ST_CAL = 1: Start self-calibration.			
2, 4, 5	AGND	Analog Ground			
3, 6	AV <sub>DD</sub>	Analog Power Supply, +5V ±5%			
7	DOR	Data Out-of-Range Bit			
8	D15	Bit 15 (MSB)			
9	D14	Bit 14			
10	D13	Bit 13			
11	D12	it 12			
12	D11	Bit 11			
13	D10	Bit 10			
14	D9	Bit 9			
15	D8	Bit 8			
16	DRV <sub>DD</sub>	Digital Power Supply for the Output Drivers. +3V to +5.25V, DRV <sub>DD</sub> ≤ DV <sub>DD</sub>			
17, 28, 29	DGND	Digital Ground			
18	D7	Bit 7			
19	D6	Bit 6			
20	D5	Bit 5			
21	D4	Bit 4			
22	D3	Bit 3			
23	D2	Bit 2			
24	D1	Bit 1			
25	D0	Bit 0 (LSB)			
26	TEST1	Test Pin 1. Do not connect.			
27, 30	DV <sub>DD</sub>	Digital Power Supply, +3V to +5.25V			
31	CLK	Input Clock. Receives power from AVDD to reduce jitter.			
32	DAV	Data Valid Clock. This clock can be used to transfer the data to a memory or any other data acquisition system.			
33	OE	Output Enable. OE = 0: D0-D15 and DOR are high impedance. OE = 1: All bits are active.			
34	TEST0	Test Pin 0. Do not connect.			
35	СМ	Common-Mode Voltage. Analog Input. Drive midway between positive and negative reference voltages.			
36	RFPF	Positive Reference Voltage, Force Input			
37	RFPS	Positive Reference Voltage, Sense Input			
38	RFNF	Negative Reference Voltage, Force Input			
39	RFNS	Negative Reference Voltage, Sense Input			
40	INP	Positive Input Voltage			
41, 42	N.C.	Not Connected. No internal connection.			
43	INN	Negative Input Voltage			
44	END_CAL	Digital Output for End of Calibration.  END_CAL = 0: Calibration in progress.  END_CAL = 1: Normal conversion mode.			

## \_Detailed Description

#### Converter Operation

The MAX1200 is a 16-bit, monolithic analog-to-digital converter (ADC) capable of conversion rates up to 1Msps. It uses a multistage, fully differential, pipelined architecture with digital error correction and self-calibration to provide typically 91dB spurious-free dynamic range at a 1Msps sampling rate. It also provides excellent SNR and THD performance up to the Nyquist frequency. This makes the device suitable for applications such as data acquisition, high-resolution imaging, scanners, digital communication, and instrumentation.

Figure 1 shows the simplified, internal structure of the ADC. A switched-capacitor, pipelined architecture is used to digitize the signal at a high throughput rate. The first four stages of the pipeline use a low-resolution quantizer to approximate the input signal. The multiplying digital-to-analog converter (MDAC) stage is used to subtract the quantized analog signal from the input. The residue is then amplified with a fixed gain and passed on to the next stage. The accuracy of the converter is improved by a digital calibration algorithm which corrects for mismatches between the capacitors in the switched-capacitor MDAC. Note that the pipeline

introduces latency of four sampling periods between the input being sampled and the output appearing at D15-D0.

While the device can handle both single-ended or differential inputs (see the *Requirements for Reference and Analog Signal Inputs* section), the latter mode of operation will guarantee best THD and SFDR performance. The differential input provides the following advantages compared to a single-ended operation:

- Twice as much signal input span
- Common-mode noise immunity
- Virtual elimination of the even-order harmonics
- Less stringent requirements on the input signal processing amplifiers

#### Requirements for Reference and Analog Signal Inputs

Fully differential switched-capacitor circuits (SC) are used for both the reference and analog inputs (Figure 2). This allows either single-ended or differential signals to be used in the reference and/or analog signal paths. The signal voltage on these pins (INP, INN, RFP\_, RFN\_) should never exceed the analog supply rail,  $AV_{DD}$ , nor fall below ground.

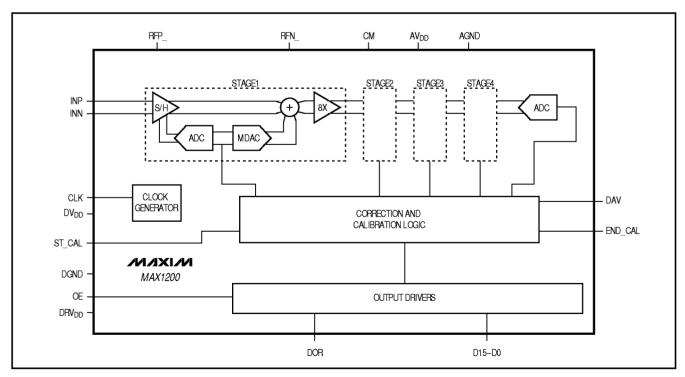


Figure 1. Internal Functional Diagram

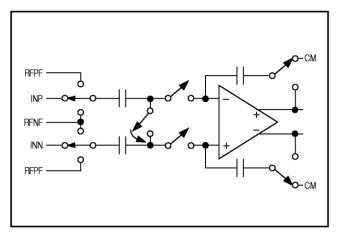


Figure 2. Simplified MDAC Architecture

#### Choice of Reference

It is important to choose a low-noise reference such as the MAX6341, which can provide both excellent load regulation and low temperature drift. The equivalent input circuit for the reference pins is shown in Figure 3. Note that the reference pins drive approximately  $1 \mathrm{k}\Omega$  of resistance on-chip. They also drive a switched capacitor of 21pF. To meet the dynamic performance, the reference voltage is required to settle to 0.0015% within one clock cycle. Carefully choose an appropriate driving circuit (Figure 4). The capacitors at the reference pins (RFPF, RFNF) provide the dynamic charge required during each clock cycle, while the op amps ensure accuracy of the reference signals. These capacitors must have low dielectric-absorption characteristics, such as polystyrene or teflon capacitors.

The reference pins can be connected to either single-ended or differential voltages within the specified maximum levels. Typically the positive reference pin (RFPF) would be driven to +4.096V, and the negative reference pin (RFNF) connected to analog ground for best SNR performance. If THD performance is more important to the application than signal-to-noise ratio, choose a lower level, differential voltage such as  $V_{RFPS} = +3.5V$  and  $V_{RFNS} = +1.5V$ .

There are sense pins, RFPS and RFNS, which can be used with external amplifiers to compensate for any resistive drop on these lines, internal or external to the chip. Ensure a correct reference voltage by using proper Kelvin connections at the sense pins.

#### Common-Mode Voltage

The switched-capacitor input circuit at the analog input allows signals between AGND and the analog power supply. Since the common-mode voltage has a strong

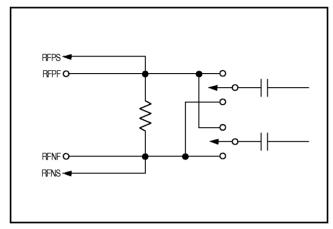


Figure 3. Equivalent Input at the Reference Pins. The sense pins should not draw any DC current.

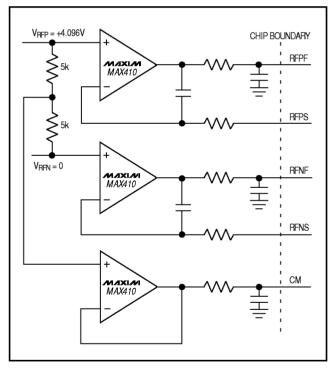


Figure 4. Drive Circuit for Reference Pins and Common-Mode Pin

influence on the performance of the ADC, the best results are obtained by choosing  $V_{CM} = (V_{RFPS} + V_{RFNS})$  / 2. This can be achieved by using a resistive divider between the two reference potentials. Figure 4 shows a typical driving circuit for good dynamic performance.

#### Analog Signal Conditioning

For single-ended inputs, the negative analog input pin (INN) is connected to the common-mode voltage pin (CM) and the positive analog input pin (INP) is connected to the input.

To take full advantage of the ADC's superior AC performance up to the Nyquist frequency, drive the chip with differential signals. In communication systems the signals may inherently be available in differential mode; however medical and/or other applications may only provide single-ended inputs. In this case, convert the single-ended signals into differential ones by using the circuit recommended in Figure 5. Use low-noise, wideband amplifiers, such as the MAX4108, to maintain the signal purity over the full-power bandwidth of the MAX1200 input.

Lowpass or bandpass signals may be required to improve the signal-to-noise and distortion of the incoming signal. For low-frequency signals (<100kHz), active filters may be used. For higher frequencies, passive filters are more convenient.

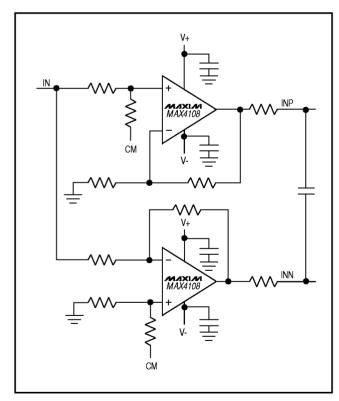


Figure 5. A simple circuit generates differential signals from a single-ended input referred to analog ground. The common-mode voltage at INP and INN is the same as CM.

# Single-Ended to Differential Conversion Using Transformers

An alternative single-ended to differential-ended conversion method is a balun transformer such as the CTX03-13675 from Coiltronics. An important benefit of these transformers is their ability to level-shift single-ended signals referred to ground on the primary side to optimum common-mode voltages on the secondary side. At frequencies below 20kHz the transformer core begins to saturate, causing odd-order harmonics.

#### Clock Source Requirements

Pipelined ADCs typically need a 50% duty cycle clock. To avoid this constraint, the MAX1200 provides a divide-by-two circuit to relax this requirement. The clock generator should be chosen commensurate with the frequency range, amplitude, and slew rate of the signal source. If the slew rate of the input signal is small, the jitter requirement on the clock is relaxed. However, if the slew rate is high, the clock jitter needs to be kept at a minimum. For a full-scale amplitude input sine wave, the maximum possible signal-to-noise ratio (SNR) due completely to clock jitter is given by:

$$SNR_{MAX} = \frac{1}{2 \cdot \pi \cdot f_{|N} \cdot \sigma_{J|TTER}}$$

For example, if f<sub>IN</sub> is 500kHz and  $\sigma_{JITTER}$  is 10ps RMS, then the SNR limit due to jitter is about 90dB. Generating such a clock source requires a low-noise comparator and a low-phase-noise signal generator. The clock circuit shown in Figure 6 is a possible solution.

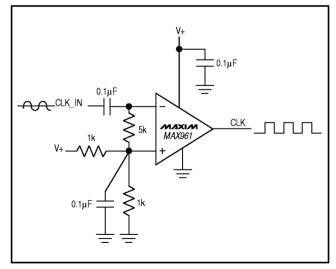


Figure 6. Clock Generation Circuit Using Low-Noise Comparator

#### Calibration Procedure

Since the MAX1200 is based on a pipelined architecture, low-resolution quantizers ("coarse ADCs") are used to approximate the input signal. MDACs of the same resolution are then used to reconstruct the input signal, which is subtracted from the input and the residue amplified by the SC gain stage. This residue is then passed on to the next stage.

The accuracy of the MAX1200 is limited by the precision of the MDAC, which is strongly dependent on the matching of the capacitors used. The mismatch between the capacitors is determined and stored in an on-chip memory, which is later used during the conversion of the input signal.

During the calibration procedure, the clock must be running continuously. ST\_CAL (start of calibration) is initiated by a positive pulse with a minimum width of four clock cycles, but not longer than about 17,400 clock cycles (Figure 8).

The ST\_CAL input may be asynchronous with the clock, since it is retimed internally. With ST\_CAL activated, END\_CAL goes low one or two clock cycles later and remains low until the calibration is complete. During this period, the reference voltages must be stable to less than 0.01%; otherwise the calibration will be invalid. During calibration, the analog inputs INP and INN are not used; however, better performance is achieved if these inputs are static. Once END\_CAL goes high (indicating that the calibration procedure is complete), the ADC is ready for conversion.

Once calibrated, the MAX1200 is insensitive to small changes ( $\pm 5\%$ ) in power-supply voltage or temperature. Following calibration, if the temperature changes more than  $\pm 20^{\circ}$ C, the device should be recalibrated to maintain optimum performance.

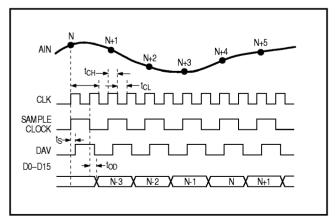


Figure 7. Main Timing Diagram

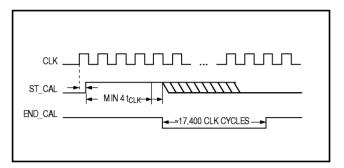


Figure 8. Timing for Start and End of Calibration

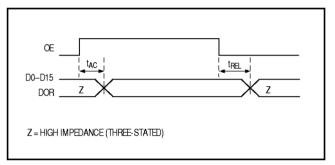


Figure 9. Timing for Bus Access and Bus Relinquish— Controlled by Output Enable (OE)

#### Two's Complement Output

The MAX1200 outputs data in two's complement format. Table 1 shows how to convert the various full-scale inputs into their two's complement output codes.

## \_Applications Information

#### Signal-to-Noise Ratio (SNR)

For a waveform perfectly reconstructed from digital samples, the theoretical maximum SNR is the ratio of full-scale analog input (RMS value) to the RMS quantization error (residual error). The ideal, theoretical minimum analog-to-digital noise is caused by quantization error only and results directly from the ADC's resolution (N bits):

$$SNR(MAX) = (6.02 \cdot N + 1.76)dB$$

In reality, there are other noise sources besides quantization noise including thermal noise, reference noise, clock jitter, etc. Therefore, SNR is computed by taking the ratio of the RMS signal to the RMS noise which includes all spectral components minus the fundamental, the first nine harmonics, and the DC offset.

**Table 1. Two's Complement Output Codes** 

SCALE	OFFSET BINARY	ONE'S COMPLEMENT	TWO'S COMPLEMENT
+FSR - 1LSB	1111 1111	0111 1111	0111 1111
+3/4FSR	1110 0000	0110 0000	0110 0000
+1/2FSR	1100 0000	0100 0000	0100 0000
+1/4FSR	1010 0000	0010 0000	0010 0000
+0	1000 0000	0000 0000	0000 0000
-0			1111 1111
-1/4FSR	0110 0000	1110 0000	1101 1111
-1/2FSR	0100 0000	1100 0000	1011 1111
-3/4FSR	0010 0000	1010 0000	1001 1111
-FSR+1LSB	0000 0001	1000 0001	1000 0000
-FSR	0000 0000	1000 0000	<del></del>

Signal-to-Noise Plus Distortion (SINAD)

SINAD is the ratio of the fundamental input frequency's RMS amplitude to all other ADC output signals:

SINAD (dB) = 20log [Signal<sub>RMS</sub> / (Noise + Distortion)<sub>RMS</sub>]

#### Effective Number of Bits (ENOB)

ENOB indicates the global accuracy of an ADC at a specific input frequency and sampling rate. An ideal ADC's error consists of quantization noise only. With an input range equal to the full-scale range of the ADC, the effective number of bits can be calculated as follows:

$$ENOB = (SINAD - 1.76) / 6.02$$

Total Harmonic Distortion (THD) THD is the ratio of the RMS sum of the first nine harmonics of the input signal to the fundamental itself. This is expressed as:

THD = 20log 
$$\frac{\sqrt{\left(V_{2}^{2} + V_{3}^{2} + V_{4}^{2} + \dots + V_{9}^{2}\right)}}{V_{1}}$$

where  $V_1$  is the fundamental amplitude, and  $V_2$  through  $V_9$  are the amplitudes of the 2nd through 9th-order harmonics.

Spurious-Free Dynamic Range (SFDR)

SFDR is the ratio of RMS amplitude of the fundamental (maximum signal component) to the RMS value of the next largest spurious component, excluding DC offset.

Grounding and Power-Supply Decoupling Grounding and power-supply decoupling strongly influence the performance of the MAX1200. At 16-bit resolution, unwanted digital crosstalk may couple through the input, reference, power supply, and ground connections; this adversely affects the SNR or SFDR. In addition, electromagnetic interference (EMI) can either couple into or be generated by the MAX1200. Therefore, grounding and power-supply decoupling guidelines should be closely followed.

First, a multilayer printed circuit board (PCB) with separate ground and power-supply planes is recommended. Run high-speed signal traces directly above the ground plane. Since the MAX1200 has separate analog and digital ground buses (AGND and DGND respectively), the PCB should also have separate analog and digital ground sections connected at only one point (star ground). Digital signals should run above the digital ground plane and analog signals should run above the analog ground plane. Digital signals should be kept far away from the sensitive analog inputs, reference input senses, common-mode input, and clock input.

The MAX1200 has three power-supply inputs: analog VDD (AVDD), digital VDD (DVDD), and drive VDD (DRVDD). Each AVDD input should be decoupled with parallel ceramic chip capacitors of values  $0.1\mu F$  and  $0.001\mu F$ , with these capacitors as close to the pin as possible and with the shortest possible connection to the ground plane. The DVDD pins should also have separate  $0.1\mu F$  capacitors again adjacent to their respective pins, as should the DRVDD pin. Minimize the digital load capacitance. However, if the total load capacitance on each digital output exceeds 20pF, the DRVDD decoupling capacitor should be increased or, preferably, digital buffers should be added.

The power-supply voltages should also be decoupled with large tantalum or electrolytic capacitors at the point they enter the PCB. Ferrite beads with additional decoupling capacitors forming a pi network may improve performance.

The analog power-supply input (AV<sub>DD</sub>) for the MAX1200 is typically +5V while the digital supplies can vary from +3V to +5V. Usually, DV<sub>DD</sub> and DRV<sub>DD</sub> pins

are connected to the same power supply. Note that the DV<sub>DD</sub> supply voltage must be greater than or equal to the DRV<sub>DD</sub> voltage. For example, a digital +3.3V supply could be connected to DRV<sub>DD</sub> while a cleaner +5V supply is connected to DV<sub>DD</sub>, resulting in slightly improved performance. Alternatively, the +3.3V supply could be connected to both DRV<sub>DD</sub> and DV<sub>DD</sub>. However, the +3.3V supply must **not** be connected to DV<sub>DD</sub> while the +5V supply is connected to DRV<sub>DD</sub> (Table 2).

Table 2. Power-Supply Voltage Combinations

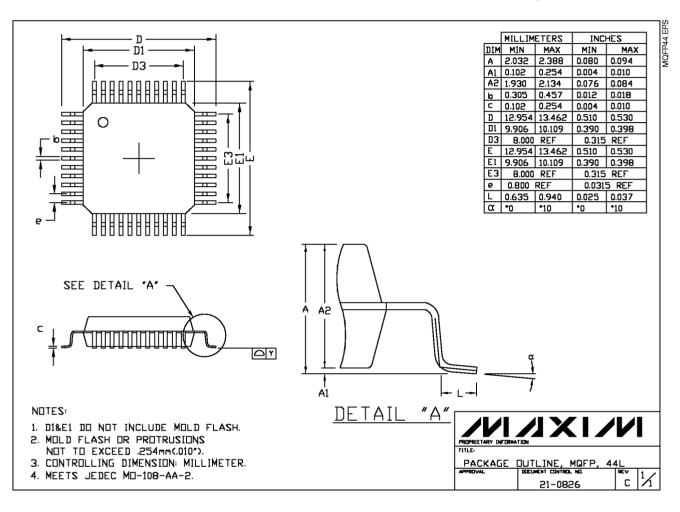
AV <sub>DD</sub> (V)	DV <sub>DD</sub> (V)	DRV <sub>DD</sub> (V)	ALLOWED/ NOT ALLOWED
+5	+5	+5	Allowed
+5	+5	+3.3	Allowed
+5	+3.3	+3.3	Allowed
+5	+3.3	+5	Not Allowed

\_Chip Information

TRANSISTOR COUNT: 56,577
SUBSTRATE CONNECTED TO AGND



## Package Information



# MAX1200

# +5V Single-Supply, 1Msps, 16-Bit Self-Calibrating ADC

**NOTES** 

**NOTES** 

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